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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Connell et al.

**Serial No.:** 10/706,212

**Filed:** November 12, 2003

**For:** WAFER BACK SIDE COATING TO  
BALANCE STRESS FROM PASSIVATION  
LAYER ON FRONT OF WAFER AND BE  
USED AS A DIE ATTACH ADHESIVE

**Confirmation No.:** 6326

**Examiner:** G. Eckert II

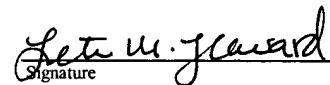
**Group Art Unit:** 2815

**Attorney Docket No.:** 2269-5083.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

March 17, 2005  
Date

  
Signature

Leta M. Howard  
Name (Type/Print)

**SUPPLEMENTAL AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing which begins on page 8 of this paper.

**Remarks** begin on page 12 of this paper.